

## CLAIMS

1. A process for preparing an aramid laminate, which comprises impregnating a surface and an interior of an aramid paper with a liquid crystal polymer, and laminating a layer comprising an aramid paper and a layer comprising a liquid crystal polymer.

2. The process for preparing an aramid laminate according to claim 1, wherein the liquid crystal polymer is a liquid crystal polyester resin composition in which (A) liquid crystal polyester is a continuous phase and (B) a copolymer having a functional group having reactivity with liquid crystal polyester is a dispersion phase.

3. The process for preparing an aramid laminate according to claim 2, wherein the liquid crystal polyester resin composition is a composition comprising 56.0 to 99.9% by weight of (A) liquid crystal polyester, and 44.0 to 0.1% by weight of (B) a copolymer having a functional group having reactivity with liquid crystal polyester.

4. The process for preparing an aramid laminate according to claim 1, wherein a layer comprising an aramid paper and a layer comprising a liquid crystal polymer are thermally fused

in a temperature range of a temperature lower than a flowing temperature of a liquid crystal polymer by 30°C to lower than 400°C.

5. The process for preparing an aramid laminate according to claim 4, wherein thermal fusing is performed at a pressure of a planar pressure of 10 kg/cm<sup>2</sup> or higher or a linear pressure of 20 kg/cm or higher.

6. The process for preparing an aramid laminate according to claim 1 or 2, wherein an aramid paper and a liquid crystal polymer-film are thermally fused.

7. A circuit substrate characterized by comprising an aramid laminate according to claim 1.